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TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

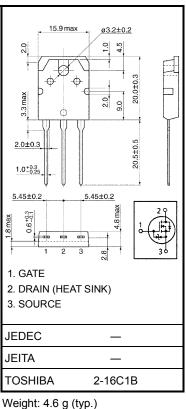
2SK2604

Switching Regulator Applications

- Low drain-source ON resistance $: RDS (ON) = 1.9 \Omega (typ.)$
- High forward transfer admittance $: |Y_{fs}| = 3.8 \text{ S (typ.)}$
- Low leakage current $: IDSS = 100 \ \mu A \ (max) \ (VDS = 640 \ V)$
- Enhancement mode : $V_{th} = 2.0 \sim 4.0 V (V_{DS} = 10 V, I_D = 1 mA)$

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	800	V	
Drain-gate voltage (R	_{GS} = 20k Ω)	V _{DGR}	800	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	۱ _D	5	А	
	Pulse (Note 1)	I _{DP}	15	А	
Drain power dissipation	n (Tc = 25°C)	PD	125	W	
Single pulse avalanche	e energy (Note 2)	E _{AS}	370	mJ	
Avalanche current		I _{AR}	5	A	
Repetitive avalanche e	energy (Note 3)	E _{AR}	12.5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	

Absolute Maximum Ratings (Ta = 25°C)



Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.0	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	50	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 27 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Unit: mm

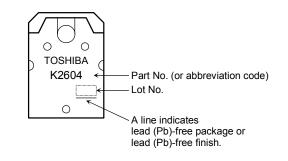
Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V		—	±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V		—	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 640 V, V _{GS} = 0 V	-	—	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	800	_		V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	—	4.0	V
Drain-source Ol	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 3 A,		1.9	2.2	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 15 V, I _D = 3 A	1.0	3.8	—	S
Input capacitance Reverse transfer capacitance		C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		1080	_	pF
		C _{rss}			16	_	
Output capacitance		Coss	1		105	—	
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{}_{0V} \int I_{D} \stackrel{I_{D}=3A}{}_{0V} V_{out}$		40	_	- ns
	Turn-on time	t _{on}		_	80	_	
	Fall time	t _f		_	40	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, t _w =10µs	_	140	_	
Total gate charge (gate-source plus gate-drain)		Qg	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 5 A		34	_	nC
Gate-source charge		Q _{gs}			16	_	
Gate-drain ("miller") Charge		Q _{gd}			18		

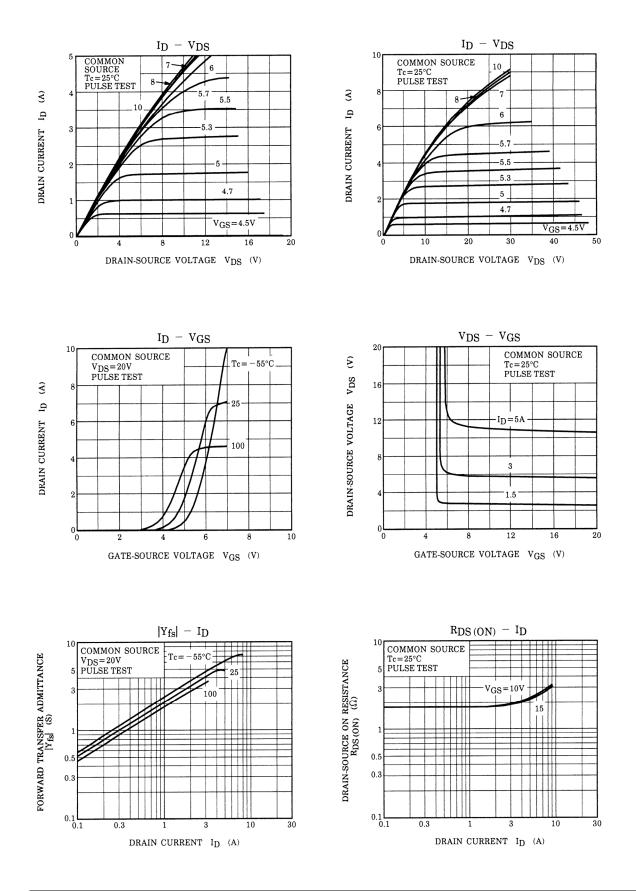
Source–Drain Ratings and Characteristics (Ta = 25°C)

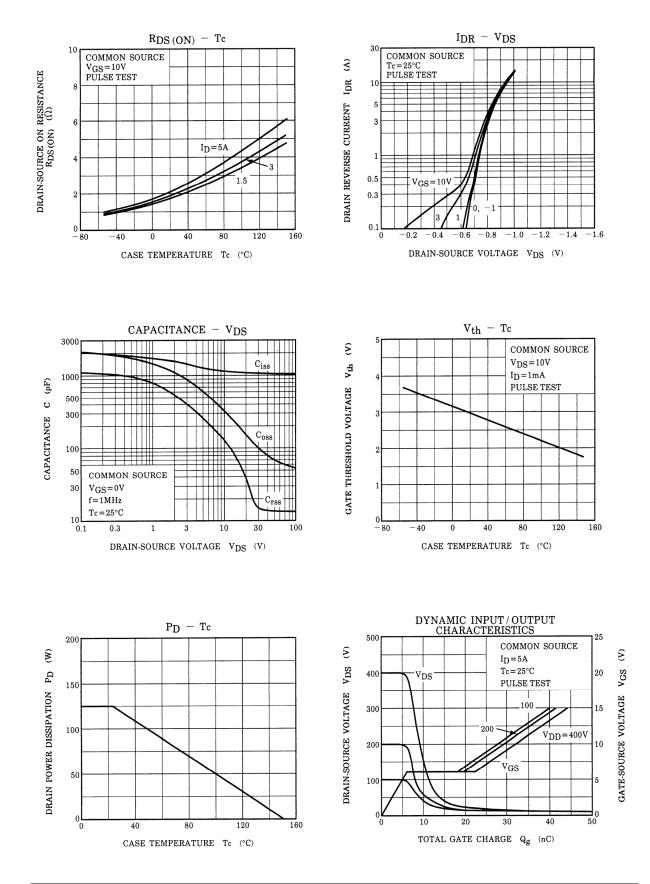
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	5	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	15	A
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	trr	I _{DR} = 5 A, V _{GS} = 0 V, dI _{DR} / dt = 100 A / μs	—	1000	—	ns
Reverse recovery charge	Q _{rr}		_	7.5	-	μC

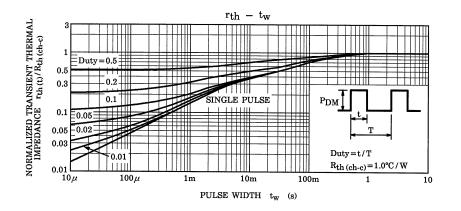
Marking

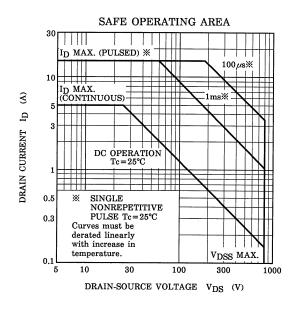


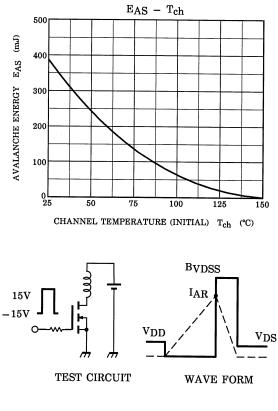
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$$R_{G} = 25 \Omega$$

$$V_{DD} = 90 \text{ V}, L = 27 \text{ mH}$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BV_{DSS}}{BV_{DSS} - V_{DD}}\right)$$

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